

## General Description

The WSD4080DN56 is the highest performance trench N-Channel MOSFET with extreme high cell density, which provide excellent  $R_{DS(ON)}$  and gate charge for most of the synchronous buck converter applications.

The WSD4080DN56 meet the RoHS and Green Product requirement, 100%  $E_{AS}$  guaranteed with full function reliability approved.

## Features

- Advanced high cell density Trench technology
- Super Low Gate Charge
- Excellent  $CdV/dt$  effect decline
- 100%  $E_{AS}$  Guaranteed
- Green Device Available

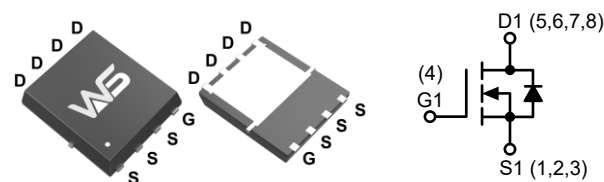
## Product Summary

$BV_{DSS}$	$R_{DS(ON)}$	$I_D$
40V	4.5m $\Omega$	85A

## Applications

- Battery protection
- LoLoad switch
- Uninterruptible power supply

## DFN5X6-8L Pin Configuration



## Absolute Maximum Ratings ( $T_C=25^{\circ}\text{C}$ , Unless Otherwise Noted)

Symbol	Parameter	Rating	Units
$V_{DS}$	Drain-Source Voltage	40	V
$V_{GS}$	Gate-Source Voltage	$\pm 20$	
$I_D@T_C=25^{\circ}\text{C}$	Continuous Drain Current, $V_{GS} @ 10V^1$	85	A
$I_D@T_C=100^{\circ}\text{C}$	Continuous Drain Current, $V_{GS} @ 10V^1$	58	
$I_{DM}$	Pulse Drain Current <sup>2</sup>	100	
$E_{AS}$	Single Pulse Avalanche Energy <sup>3</sup>	110.5	mJ
$I_{AS}$	Avalanche Current	47	A
$P_D@T_C=25^{\circ}\text{C}$	Total Power Dissipation	52.1	W
$T_{STG}$	Storage Temperature Range	-55 to 150	$^{\circ}\text{C}$
$T_J$	Operating Junction Temperature Range	-55 to 150	

## Thermal Data

Symbol	Parameter	Typ.	Max.	Units
$R_{\theta JA}$	Thermal Resistance Junction-Ambient <sup>1</sup>	---	62	$^{\circ}\text{C/W}$
$R_{\theta JC}$	Thermal Resistance Junction-Case <sup>1</sup>	---	2.4	

**Electrical Characteristics ( $T_J=25^{\circ}\text{C}$ , Unless Otherwise Noted)**

Symbol	Parameter	Conditions	Min.	Typ.	Max.	Units
$BV_{DSS}$	Drain-Source Breakdown Voltage	$V_{GS}=0V$ , $I_D=250\mu A$	40	---	---	V
$R_{DS(ON)}$	Static Drain-Source On-Resistance <sup>2</sup>	$V_{GS}=10V$ , $I_D=10A$	---	4.5	6.5	m $\Omega$
		$V_{GS}=4.5V$ , $I_D=5A$	---	6.4	8.5	
$V_{GS(th)}$	Gate Threshold Voltage	$V_{GS}=V_{DS}$ , $I_D=250\mu A$	1.0	1.5	2.5	V
$I_{DSS}$	Drain-Source Leakage Current	$V_{DS}=32V$ , $V_{GS}=0V$ , $T_J=25^{\circ}\text{C}$	---	---	1.0	$\mu A$
		$V_{DS}=32V$ , $V_{GS}=0V$ , $T_J=55^{\circ}\text{C}$	---	---	5.0	
$I_{GSS}$	Gate-Source Leakage Current	$V_{GS}=\pm 20V$ , $V_{DS}=0V$	---	---	$\pm 100$	nA
$g_{fs}$	Forward Transconductance	$V_{DS}=10V$ , $I_D=5A$	---	27	---	S
$Q_g$	Total Gate Charge (4.5V)	$V_{DS}=20V$ , $V_{GS}=4.5V$ , $I_D=10A$	---	20	---	nC
$Q_{gs}$	Gate-Source Charge		---	5.8	---	
$Q_{gd}$	Gate-Drain Charge		---	9.5	---	
$T_{d(on)}$	Turn-On Delay Time	$V_{DD}=15V$ , $V_{GS}=10V$ , $R_G=3.3\Omega$ , $I_D=1A$	---	15.2	---	ns
$T_r$	Rise Time		---	8.8	---	
$T_{d(off)}$	Turn-Off Delay Time		---	74	---	
$T_f$	Fall Time		---	7	---	
$C_{iss}$	Input Capacitance	$V_{DS}=15V$ , $V_{GS}=0V$ , $f=1.0\text{MHz}$	---	2354	---	pF
$C_{oss}$	Output Capacitance		---	215	---	
$C_{rss}$	Reverse Transfer Capacitance		---	175	---	

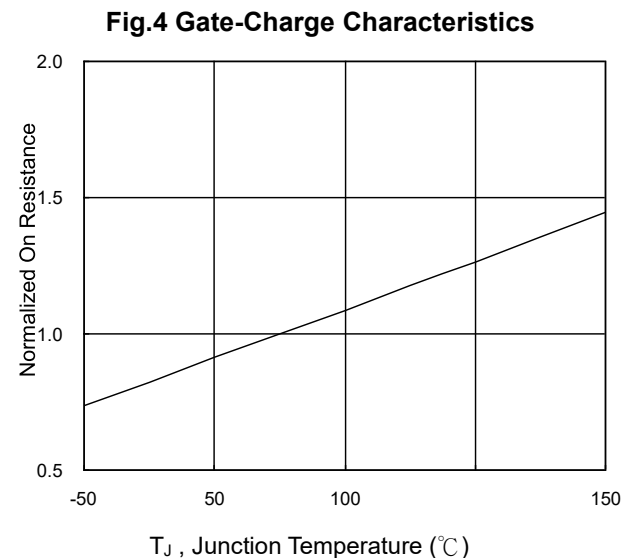
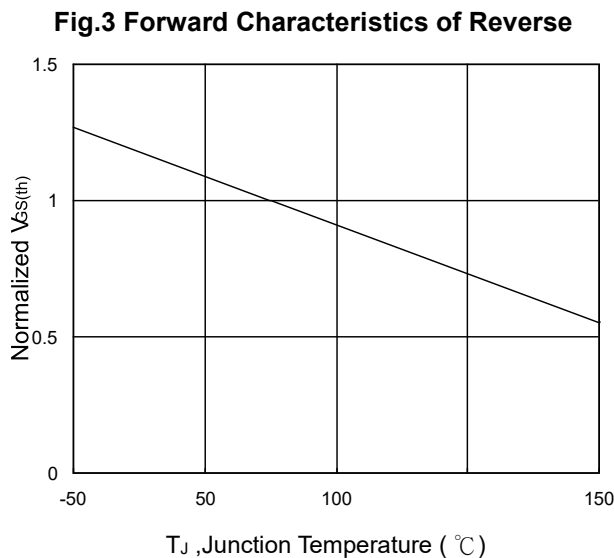
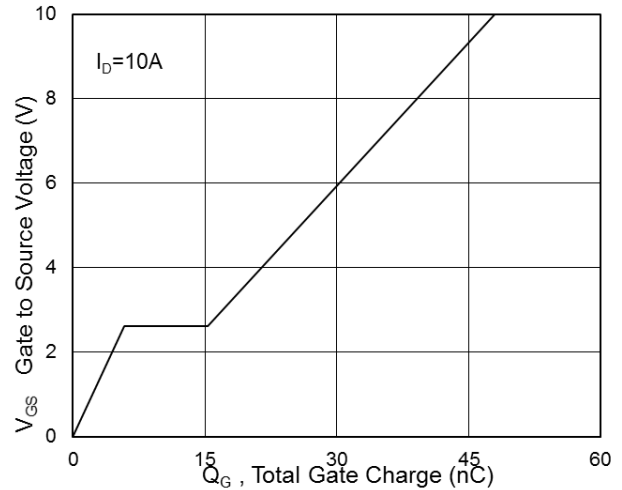
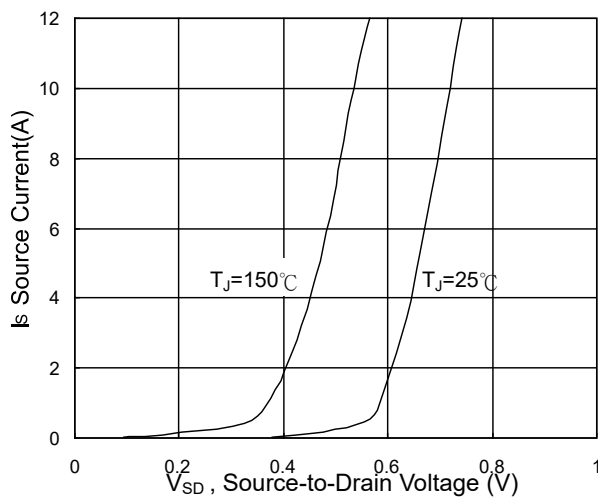
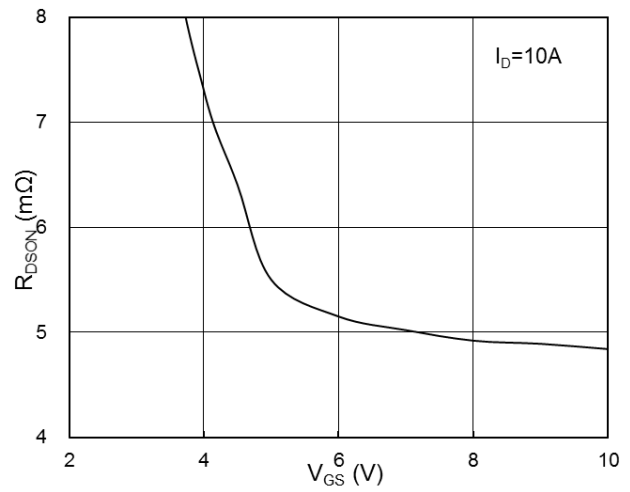
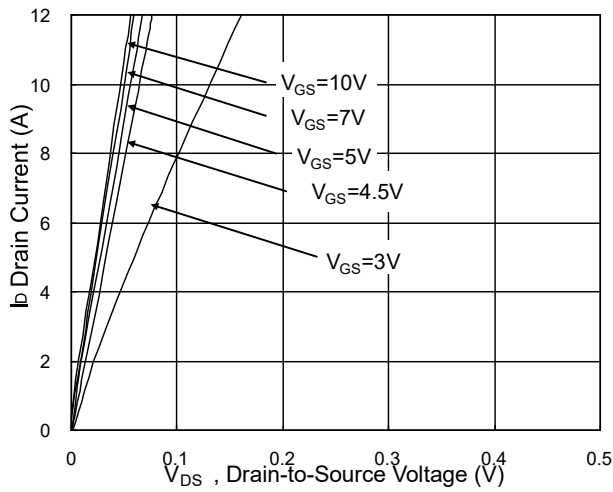
**Diode Characteristics**

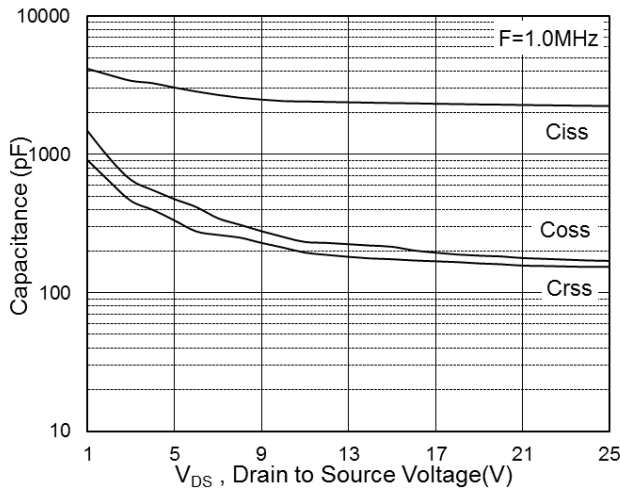
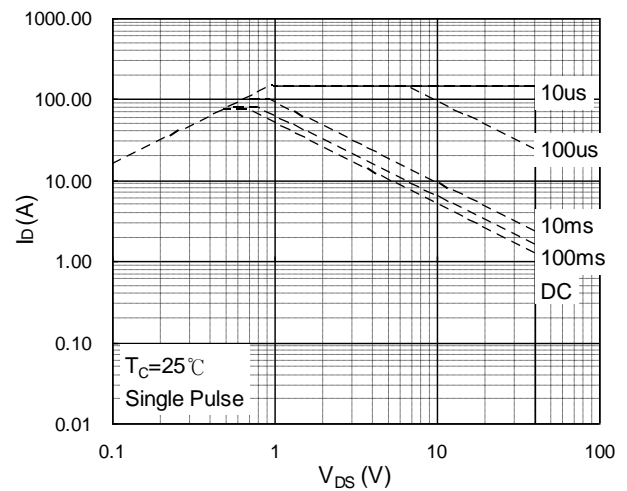
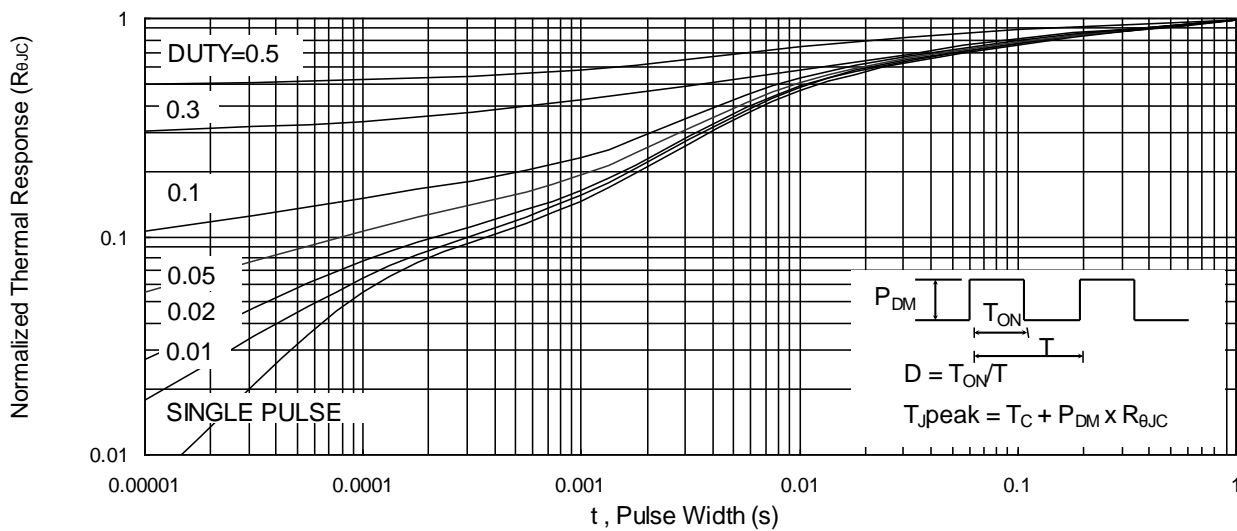
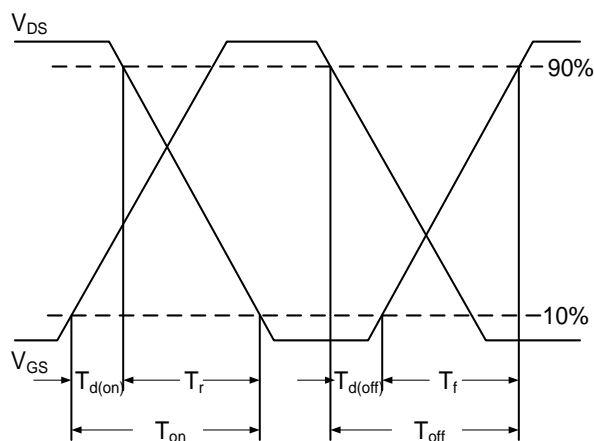
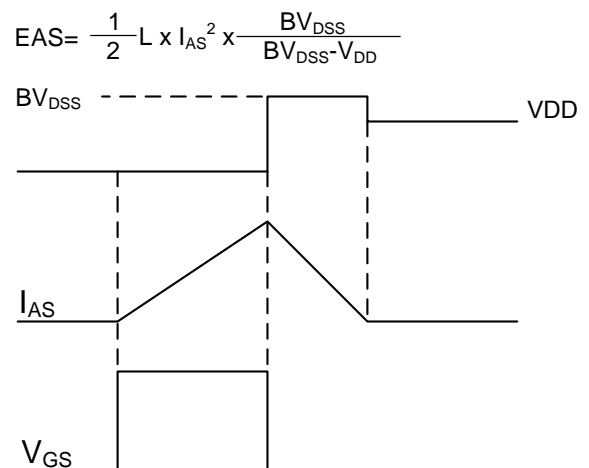
Symbol	Parameter	Conditions	Min.	Typ.	Max.	Units
$I_S$	Continuous Source Current <sup>1,5</sup>	$V_G=V_D=0V$ , Force Current	---	---	70	A
$V_{SD}$	Diode Forward Voltage <sup>2</sup>	$V_{GS}=0V$ , $I_S=1A$ , $T_J=25^{\circ}\text{C}$	---	---	1.0	V

**Note:**

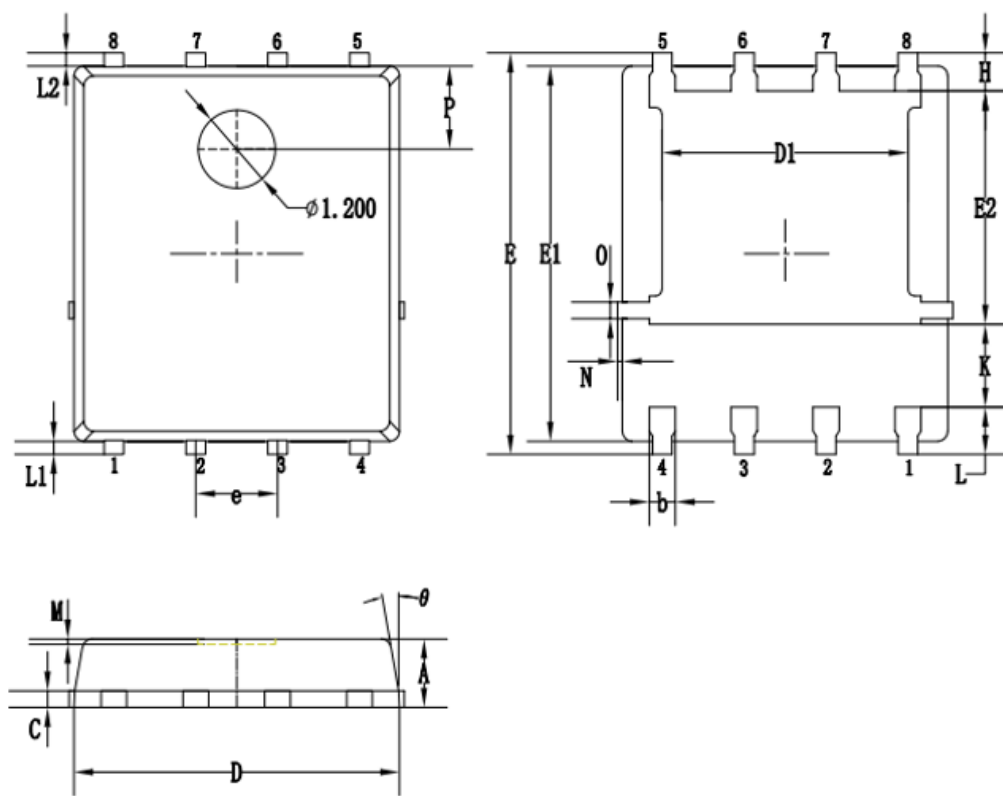
1. The data tested by surface mounted on a 1 inch<sup>2</sup> FR-4 board with 2OZ copper.
2. The data tested by pulsed, pulse width  $\leq 300\mu s$ , duty cycle  $\leq 2\%$ .
3. The  $E_{AS}$  data shows Max. rating. The test condition is  $V_{DD}=25V$ ,  $V_{GS}=10V$ ,  $L=0.1mH$ ,  $I_{AS}=47A$
4. The power dissipation is limited by  $150^{\circ}\text{C}$  junction temperature.
5. The data is theoretically the same as  $I_D$  and  $I_{DM}$ , in real applications, should be limited by total power dissipation.

## Typical Characteristics



**Typical Characteristics (Cont.)**

**Fig.7 Capacitance**

**Fig.8 Safe Operating Area**

**Fig.9 Normalized Maximum Transient Thermal Impedance**

**Fig.10 Switching Time Waveform**

**Fig.11 Unclamped Inductive Switching Wave**

## Packaging information



SYMBOLS	MILLIMETERS		
	MIN.	NOM.	MAX.
A	0.90	1.05	1.20
b	0.35	0.40	0.50
C	0.20	0.25	0.35
D	4.90	5.05	5.20
D1	3.72	3.82	3.92
E	6.00	6.15	6.30
E1	5.60	5.75	5.90
E2	3.47	3.57	3.67
e	1.27 BSC.		
H	0.48	0.58	0.68
K	1.17	1.27	1.37
L	0.64	0.74	0.84
L1/L2	0.20 REF.		
$\theta$	8°	10°	12°
M	0.08 REF.		
N	0	-	0.15
O	0.25 REF.		
P	1.28 REF.		

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